DELL SE2219H, SE2419H

1. Disassemble Procedures

S1 Turn off power Unplug cables from monitor.



Press upper edge of the back cover (start with top of monitor) with both thumbs, the rest 4 fingers pull back cover upwards. Repeat the action 2-8 position to remove back cover.

S4

S6



S2 Remove stand from monitor release button (with Philip-head screwdriver)

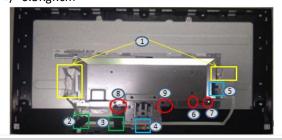


Remove 2 aluminium foil (#1 as yellow) and 2 acetate tape (#2 & #3 as green).

Remove Keypad cable & Backlight cable (#4 & #5 as blue).

Use Hexgonal screwdriver to remove 2 VGA screws 4-40 x 11.8 (#6 & #7). Torque: 4.5 +/- 0.5Kgf.cm

Use Philips-head screwdriver (Φ5 mm) to remove 2 metal frame screws M3*5 (#8 & #9). Torque: 4.5 +/- 0.5Kgf.cm

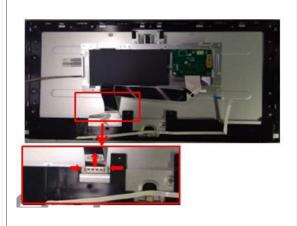


Use Philips-head screwdriver (Φ5 mm) to remove 2 screws for unlocking.

M4 x 4.5, Torque = 12 +/- 1Kgf.cm



Remove 1 aluminium foil & unplug LVDS cable.



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Flip chassis, remove mylar.
Use Philips-head screwdriver (Φ5 mm) to remove PCBAs screws.
M3 x 5 & M3 x 6 for ground screw.
Torque = 6.0 kgf +/-0.5 kgf

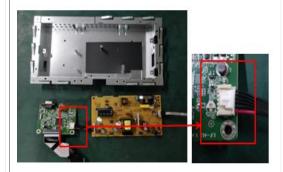


Use Philips-head screwdriver (Φ3 mm) to remove 3 screws from mid frame (to disassemble front trim).

T2 x3. Torque: 1.0 +/- 0.1Kgf.cm



S8 Remove cables from IF & power board.



Remove electrolyte capacitor >25mm height (red mark) from printed circuit boards.

Cut the glue between bulk cap and PCBA with knife – ensure cutting path within the glue, don't

touch bulk cap and PCBA.

S12



S9 Use Philips-head screwdriver (Φ3 mm) to remove 11 screws from mid-frame M3 x 4. Torque: 3.5 +/- 0.5Kgf.cm



Take out the capacitor pin solder with soldering iron.

Lift the bulk capacitor away from power board.



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2. Product Material Information

The following substances, preparation, or components should be disposed of or recovered separately from other WEEE in compliance with Article 4 of EU Council Directive 75/422/EEC.

Capacitors / Condensers (containing PCB/PCT)	Not used
Mercury containing components	Not used
Batteries	Not used
Printed circuit boards (with surface greater than 10 square cm)	Product has printed circuit boards (with surface greater than 10 square cm)
Component contain toner, ink and liquids	Not used
Plastic containing BFR	
Component and waste contain asbestos	Not used
CRT	Not used
Component contain CFC, HCFC, HGC and HC	Not used
Gas discharge lamps	Not use
LCD display > 100 cm2	Product LCD greater than 100cm2
External electric cable	Product has external cables
Component contain refractory ceramic fibers	Not used
Component contains radio-active substances	Not used
Electrolyte capacitors (height > 25mm, diameter >25mm)	Product has electrolyte capacitors (height > 25mm)

3. Tools Required

List the type and size of the tools that would typically can be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description:-

- Screwdriver (Philip head with Φ5 mm & Φ3 mm)
- Screwdriver (Hexgonal to remove VGA connectivity)
- Soldering iron
- Knife